

Electroless Metal Photo-Patterning

Electroless Metal Photo-Patterning Technology.

NANO3D provides chemicals (cleaning, catalytic resist, developer, plating) and photopatterning plating services to fabricate metal patterns including transparent metal mesh and finepitch interconnects for Display, MEMS, LED & other applications.

Key Benefits:

Selective, conformal and uniform metal patterns

- Photo-selective electroless plating to form fine-pitch metal patterns
- Step coverage of over 95% in high aspect ratios features
- WIW thickness nonuniformity of < 2% @ 1 Sigma

Optimal surface roughness and texture of the patterns

- Smooth surface morphology (Ra < 10 nm)
- Strong (111) texture

Wide variety of substrates

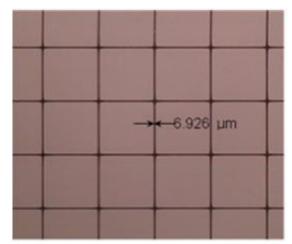
 The technology is applicable for the metallization of flexible (polymers, glass, ceramic, plastic, silicon et al.), patterned (vias & trenches) & stretchable substrates.

Better transparent electrodes

- Low cost and sheet resistance that reduces pcap charge time and enable larger displays as well as increases SNR and linearity
- High transparency and flexibility



Electroless metal deposition on flexible substrates



Transparent metal mesh fabricated by photo-selective electroless plating



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Advantages of metal mesh vs other conductive transparent electrodes

Parameters	ITO	Metal Mesh	Ag Nanowires	Carbon Nanotubes	Conductive Polymer		
Optical							
Visibility	NO	NO at 1 μm	NO	NO	NO		
Transparency	88%	Up to 90%	Up to 90%	Up to 90%	BEST		
Effect of ambient light	Moderate	Moderate	Increase Haze	Best (lowest reflectivity)	Moderate		
Moire Patterns	Yes	NO	NO	NO	NO		
Color shift	Yellow color shift (b* > 2)	Lowest (b*<0.5)	Moderate (1 <b*<2)< td=""><td>Lowest (b*<0.5)</td><td>Moderate (1<b*<2)< td=""></b*<2)<></td></b*<2)<>	Lowest (b*<0.5)	Moderate (1 <b*<2)< td=""></b*<2)<>		
Electrical							
Sheet resistance	1 Ω/Sq	<1 Ω/Sq	Low	High	High		
Physical Characteristics							
Flexibility	Poor	Good	Moderate	Best (100k times at <1 mm radius)	Best (100k times at <1 mm radius)		
Reliability							
Redundancy	NO	Yes	Yes	Yes	No		
Corrosion	Good	Moderate	Poor	Best	Moderate		
Cost							
Cost	High	Low	High	Moderate	Low		

Advantages of NANO3D's metal mesh technology

Parameters	NANO3D Cu MESH	Cu MESH by wet etching	Cu MESH fabricated by nano-imprinting	Cu MESH by flexography
Method	Direct plating on catalytic inorganic resist	Photo-lithography and Cu etching	Nano-imprinting	Flexographic printing
Environmental	OK	Waste from Cu etching	Moderate waste	OK
Adhesion	High	High	Moderate	Moderate
Line resolution	< 1 μm	< 1 μm	< 1 μm	< 1 μm
Cost	Low	High	Moderate cost	Low

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